

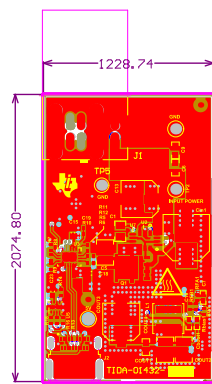
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlau				
2	Top Solder	Solder Resist	0.40mil	3.8	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	6.00mil	4.8	
5	Signal Layer 1	Copper	1.40mil		
6	Dielectric2		44.00mil	4.2	
7	Signal Layer 2	Copper	1.40mil		
8	Dielectric 3	Copper	6.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.8	
11	Bottom Overlau				

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



**DESIGN INFORMATION**

MIN. TRACK WIDTH: 8 MIL  
 MIN. CLEARANCE: 8 MIL  
 MIN. VIA PAD SIZE: 16 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL  
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

**MATERIAL:**  
 FR-408  FR-4 High Tg  OTHER \_\_\_\_\_  
 THICKNESS:  62 MIL (1.6mm) +/-10%  OTHER \_\_\_\_\_  
 TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_  
 BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

**DRILLING:**  
 REFERENCE:  AS SHOWN  NC DRILL FILES  
 PTH COPPER THICKNESS:  20-30 um  OTHER \_\_\_\_\_

**BOARD FINISH:**  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER \_\_\_\_\_  
 SOLDER RESIST COLOR:  GREEN  OTHER \_\_\_\_\_  
 MATTE  SEMI-GLOSS

SURFACE FINISH:  IMMERSION GOLD (ENIG)  ENEPIG  
 IMM. TIN/SILVER OR EQUIV  OTHER \_\_\_\_\_

ARRAY/PANEL:  CUT AND TRIM PER M1 BOARD OUTLINE  
 N.C. ROUTE  V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS ->  1  2  3  
 RoHS  OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

**ADDITIONAL REQUIREMENTS:**  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

REVISED BY: [Name] DATE: [Date]  
 APPROVED BY: [Name] DATE: [Date]

REVISION	DATE	BY	DESCRIPTION	APPROVED BY	DATE
1	01/18/2017	AVM	INITIAL RELEASE		
2	01/18/2017	AVM	DESIGN CHANGES		

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ENGINEER: <b>H. Bovenzi</b>	LAYOUT BY: <b>Bovenzi/Clanin</b>
SCALE: 1.00	ALTIM DESIGNER VERSION: 17.1.5.472

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